DS Series

1.0 Description

These delay lines provide timing control to 10 nanosecond in a SIP solder leaded three pin package. Thin film on ceramic construction provides for high reliability and high bandwidth performance. The DS1L5 B series are designed for tape and reel packaging and pick and place automated assembly.





Serial Code B

3.0 Electrical

DS1L		Serial Code S		
0.1 to 10.0 ns				
0.1 to 2.0 ns:	±0.050 ns	Time Delay	Height (H)	Form
2.25 to 5.0 ns:	±0.125 ns	0.1 to 5.0 ns	6.35 max	D
5.5 to 10.0 ns:	±0.250 ns	5 5 to 10 0 ns	9 20 max	V
0.1 to 2.0 ns:	0.10 ns steps	0.0 10 10.0 110	0.20 max	
2.25 to 5.0 ns:	0.25 ns steps			
5 to 10.0 ns:	0.50 ns steps			
50 ohm ± 5 ohm		Serial Code B		
1 ohm/ns max				
100 mA		Time Delay	Height (H)	Form
<150 ppm/°C		0.1 to 5.0 ns	6.50 max	J
>100 Mohm @ 50 Vdc			I	I
>100 Mohm @ 50 Vdc				
-40°C to +85°C				
-55°C to +125°C				
	DS1L 0.1 to 10.0 ns 0.1 to 2.0 ns: 2.25 to 5.0 ns: 5.5 to 10.0 ns: 0.1 to 2.0 ns: 2.25 to 5.0 ns: 5.5 to 10.0 ns: 5.0 to 10.0 ns: 5 to 10.0 ns: 50 ohm ± 5 ohm 1 ohm/ns max 100 mA <150 ppm/°C	DS1L 0.1 to 10.0 ns 0.1 to 2.0 ns: ±0.050 ns 2.25 to 5.0 ns: ±0.125 ns 5.5 to 10.0 ns: ±0.250 ns 0.1 to 2.0 ns: 0.10 ns steps 2.25 to 5.0 ns: 0.25 ns steps 5.5 to 10.0 ns: 0.25 ns steps 5 to 10.0 ns: 0.50 ns steps 50 ohm ± 5 ohm 1 ohm/ns max 100 mA <150 ppm/°C	DS1L Serial Code 0.1 to 10.0 ns ±0.050 ns 0.1 to 2.0 ns: ±0.125 ns 2.25 to 5.0 ns: ±0.125 ns 5.5 to 10.0 ns: ±0.250 ns 0.1 to 2.0 ns: 0.10 ns steps 2.25 to 5.0 ns: ±0.25 ns 5.5 to 10.0 ns: 0.25 ns steps 5 to 10.0 ns: 0.50 ns steps 5 to 10.0 ns: 0.50 ns steps 50 ohm ± 5 ohm Time Delay 1 ohm/ns max Time Delay 100 mA Time Delay <150 ppm/°C	DS1L Serial Code S 0.1 to 10.0 ns ±0.050 ns 2.25 to 5.0 ns: ±0.125 ns 5.5 to 10.0 ns: ±0.250 ns 0.1 to 2.0 ns: ±0.250 ns 0.1 to 2.0 ns: ±0.250 ns 0.1 to 2.0 ns: 0.10 ns steps 2.25 to 5.0 ns: 0.25 ns steps 5 to 10.0 ns: 0.50 ns steps 5 0 ohm ± 5 ohm 1 1 00 mA 100 mA <100 Mohm @ 50 Vdc





